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Attorney Docket: 2022/48819
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800

Group Art Unit: 3723

Filed: September 28, 2000

Examiner: Not Yet Assigned

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL
COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE
AND LAYER STRUCTURE MADE THEREBY

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MAY 02 2001

ADDITIONAL CLAIMS FEE CHART

Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith is a Second Preliminary Amendment
for filing and the filing fee is calculated below:

For	No. After Amendment	Highest No. Prev. Filed	No. Extra	Rate	
Total Claims	61	38	= 23	x	\$ 9/\$18 = \$414
Indep. Claims	5	3	= 2	x	\$40/\$80 = \$160
Multiple Dependent Claim Presented					\$135/\$270 = \$270
TOTAL:					\$844

XX Two checks in the amount of \$844.00 are enclosed.

XX The Commissioner is hereby authorized to charge any additional
fees which may be required, or credit any overpayment, to
Account No. 05-1323 (Docket #2022/48819). A duplicate copy
of this sheet is attached.

April 20, 2001

Respectfully submitted,

Richard R. Diefendorf
Registration No. 32,390

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Attorney Docket: 2022/48819
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L. Nelson
#7/Pre Amend B
6/7/01

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SECOND PRELIMINARY AMENDMENT

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Assistant Commissioner for Patents
Washington, D.C. 20231

OFFICE OF PETITIONS

Sir:

Please add the following new claims prior to examination:

B1
--39. A process for forming a conductive material structure on a surface of a substrate, wherein the surface of the substrate includes a top portion and cavity portions, the process comprising the steps of:

applying an electrolyte solution to the surface of the substrate while applying a first potential to the substrate so as to deposit a planar layer of a conductive material out of the electrolyte solution onto the surface including the top portion and into the cavity portions; and

reducing the thickness of the planar layer in a planar manner while continuing to apply the electrolyte solution to the surface of the substrate.

40. The process of Claim 39, wherein the step of reducing the thickness of the planar layer comprises applying a

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270.00 LF